

Design considerations of 65W active clamp flyback adaptor with MasterGaN

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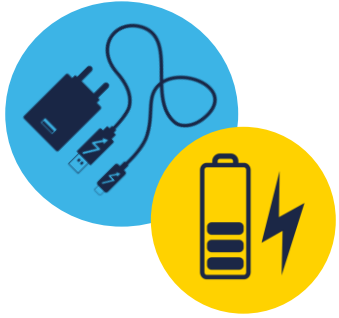
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Travel adapter development



Power Level Increasing 5W → 65W → 120W

Power Density Increasing 5W/in³ → 20W/in³ → 30W/in³

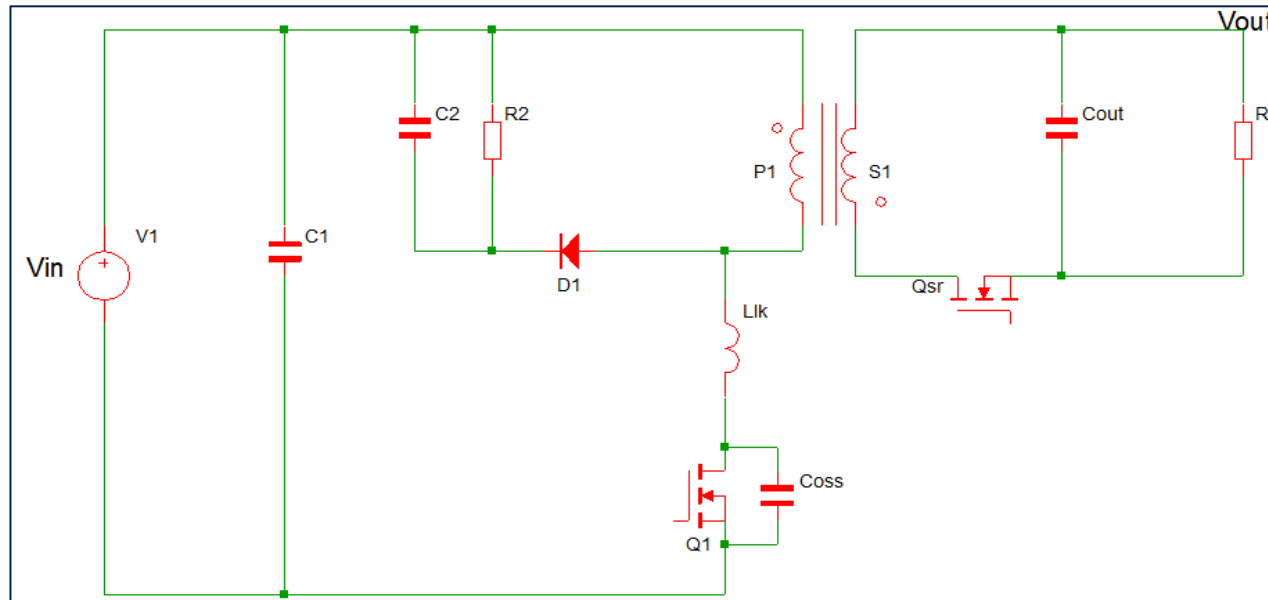
Switching frequency Increasing 60kHz → 150kHz → 350kHz



Drawbacks of flyback

Drawbacks of traditional Flyback

- High power loss and spike caused by leakage inductance of the transformer
- High switching loss of the main MOSFET due to the spike



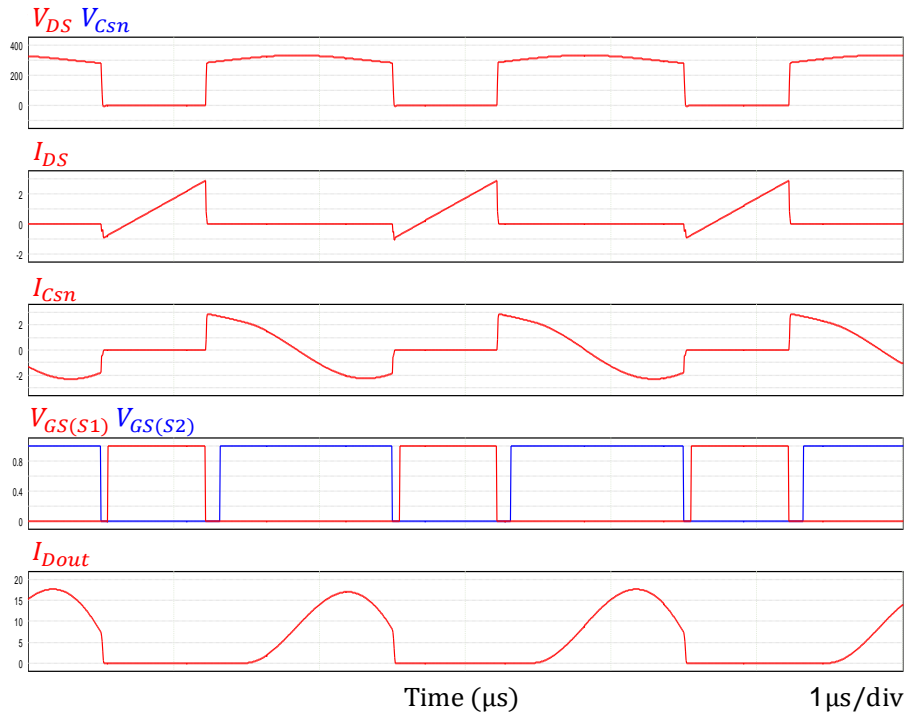
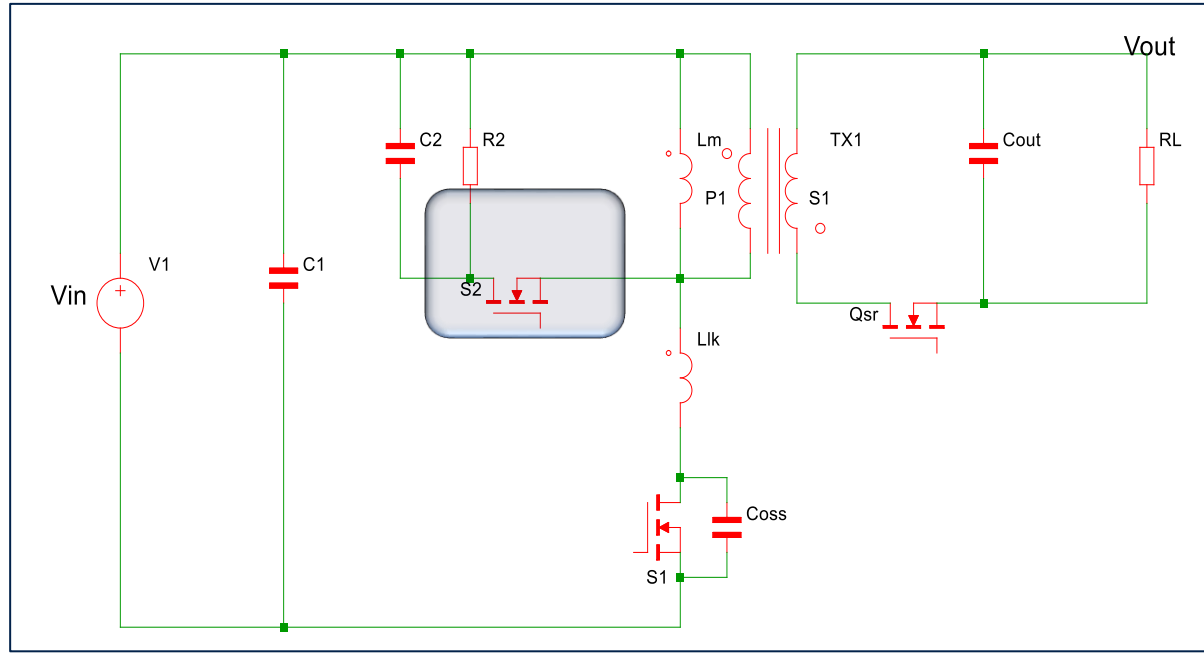
$$P_{ON} = I_{P(RMS)}^2 R_{DS(ON)}$$

$$P_{SW-ON(COSS)} = f_{SW} \int_0^{V_{DS(OFF)}} C_{OSS}(V_{ds}) V_{ds} dV_{ds}$$

$$P_{SW-OFF} = \frac{I_P^2 T_{FALL}^2}{6 C_{OSS(eq)}} f_{SW}$$



ACF used in smart charger



- The leakage inductance energy is recycled with clamp circuit, while the Turn-OFF voltage stress across the power switch is minimized
- The ZVS of the power switch is achieved and subsequently the switching losses are minimized
- Decrease the stress of the secondary rectifier diode



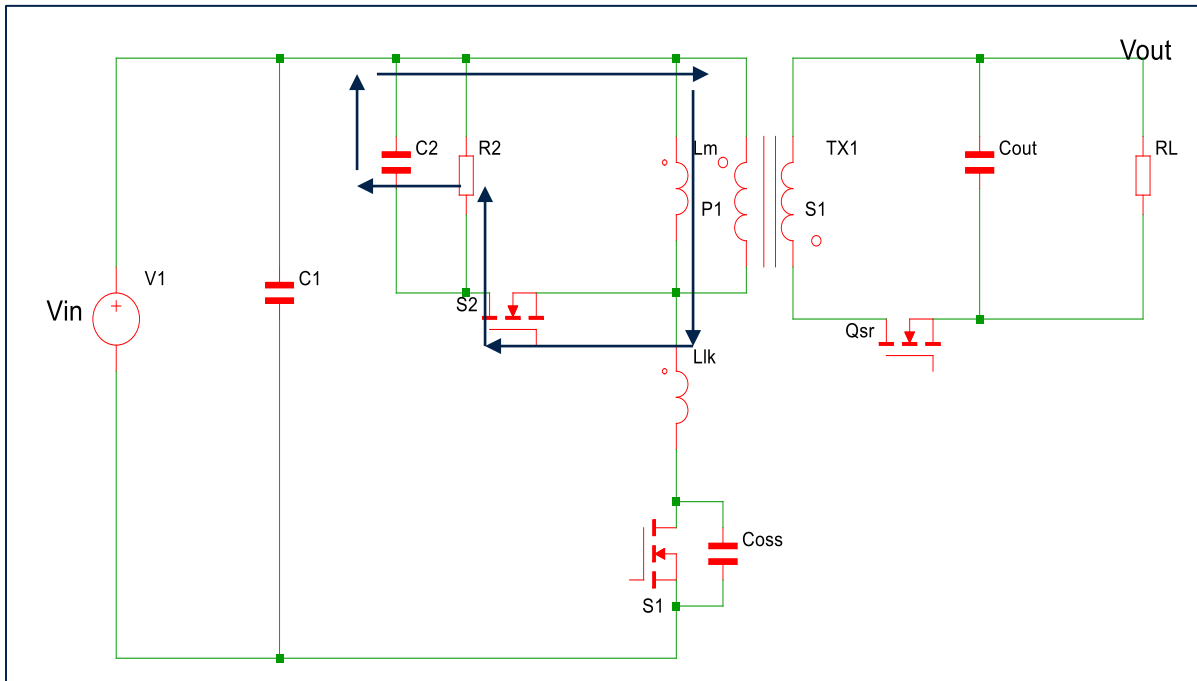
ACF used in smart charger

PROs

- The energy of the leakage inductance is recycled
- ZVS is achieved and switching losses are minimized → High efficiency and high switching frequency achievable
- Soft-switching architecture

CONs

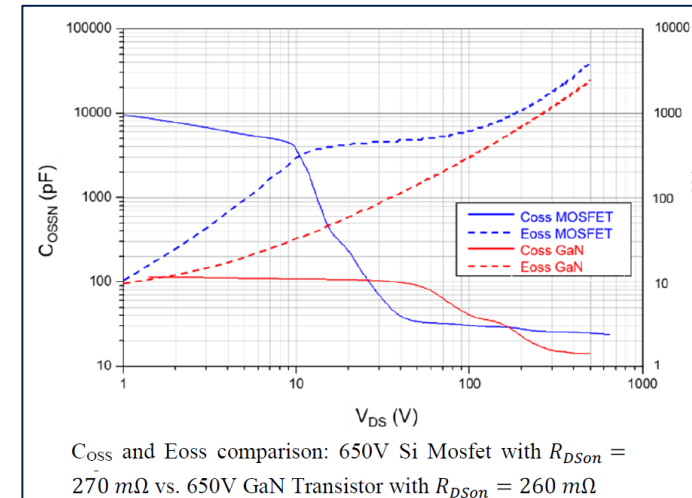
- Additional clamp power switch with dedicated high-side driver
- Increases the complexity of the controller
- Much more difficult to design and optimize compared with a standard flyback





GaN vs. Silicon based transistors

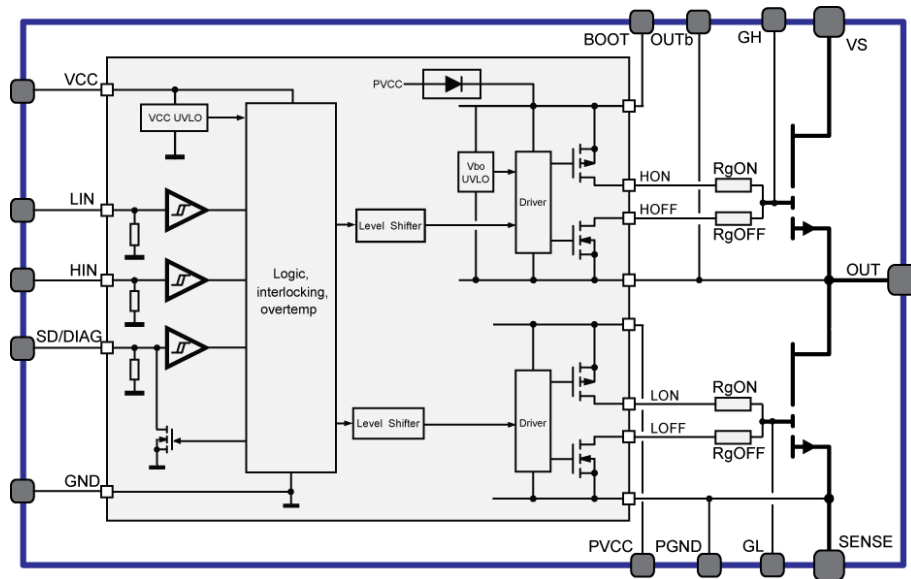
- Gallium Nitride (GaN) is a wide-bandgap (WBG) material. HEMT (High Electron Mobility Transistor) gallium nitride (GaN) transistors, or simply GaN transistor, represents a major step forward in power electronics, providing high frequency operation, increased efficiency and higher power density compared with silicon-based transistors.



| | GaN | Silicon | Comments |
|-----------------------------|-----------|---------|--|
| Qg-Gate charge | Lower | Higher | GaN with lower driver loss to achieve higher frequency & efficiency |
| Coss-Output capacitance | Lower | Higher | GaN with lower switching loss to achieve higher frequency & efficiency |
| Qrr-Reverse recovery charge | Lower | Higher | GaN suitable for higher frequency & efficiency |
| Vgs- gate voltage | Difficult | Easy | GaN need better gate drive circuit and PCB layout |
| Vsd-body diode conduction | Higher | Lower | GaN need better control of deadtime |



High power density half-bridge 650V GaN with embedded driver



GQFN 9x9

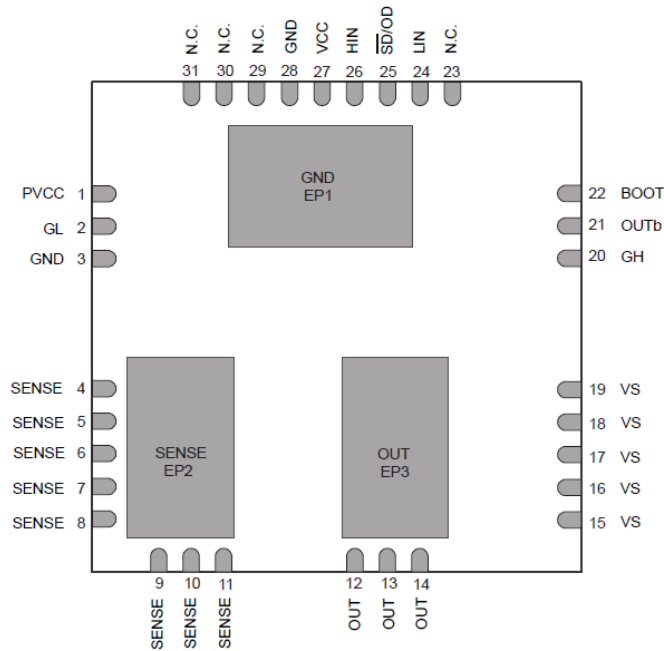
Features

- Power system-in-package integrating half-bridge gate driver and high-voltage GaN transistors:
 - BVDSS = 650 V
 - RDS(ON) = 150 mΩ
 - IDS(MAX) = 10 A
- Reverse current capability
- Zero reverse recovery loss
- UVLO protection on low-side and high-side
- Internal bootstrap diode
- Interlocking function
- Dedicated pin for shutdown functionality
- Accurate internal timing match
- 3.3 V to 15 V compatible inputs with hysteresis and pull-down
- Overtemperature protection
- Bill of material reduction
- Very compact and simplified layout
- Flexible, easy and fast design



MasterGaN1 pinout

Figure 2. Pin connection (top view)



| Pin Number | Pin Name | Type | Function |
|-------------------------------|----------|--------------------|---|
| 15, 16, 17, 18, 19 | VS | Power Supply | High voltage supply (high-side GaN Drain) |
| 12, 13, 14, EP3 | OUT | Power Output | Half-bridge output |
| 4, 5, 6, 7, 8, 9, 10, 11, EP2 | SENSE | Power Supply | Half-bridge sense (low-side GaN Source) |
| 22 | BOOT | Power Supply | Gate driver high-side supply voltage |
| 21 | OUTb | Power Supply | Gate driver high-side reference voltage, used only for Bootstrap capacitor connection. Internally connected to OUT. |
| 27 | VCC | Power Supply | Logic supply voltage |
| 1 | PVCC | Power Supply | Gate driver low-side supply voltage |
| 28, EP1 | GND | Power Supply | Logic ground |
| 3 | PGND | Power Supply | Gate driver low-side driver reference. Internally connected to SENSE. |
| 26 | HIN | Logic Input | High-Side driver logic input |
| 24 | LIN | Logic Input | Low-Side driver logic input |
| 25 | SD/OD | Logic Input-Output | Driver Shutdown input and Over-Temperature |
| 2 | GL | Output | Low-Side GaN gate. |
| 20 | GH | Output | High-Side GaN gate. |
| 23, 29, 30, 31 | N.C. | Not Connected | Leave floating |



MasterGaN1 applications and benefits

Applications

Telecom/Server Power

Power Supply for 5G
Communication
Infrastructure

EV/HEV Charging Stations

Energy Storage Systems
(UPS)

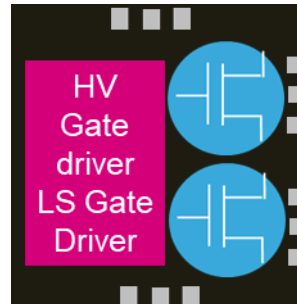
Solar DC-AC Converters

PC Power, OLED TV

High-Density AC-DC
Adapters, Fast Charging,
USB-PD

Key benefits

- Compact system solution and simplified layout
- BOM reduction: SiP with offline driver optimized for GaN
- Robust solution: driver and GaN power transistors integration
- Package GQFN 9x9
- Flexible, easy and fast design
- Scalable p2p solution for power range 30-500 W





MasterGaN family roadmap

QFN 9x9 mm² pin-to-pin scalable

One driver, many standard transistors for HB configuration



From 45 up to 400 W

MasterGaN1

Symmetrical

150 + 150 mΩ

Mass production

MasterGaN2

Asymmetrical

150 + 225 mΩ

MP Dec 2020

MasterGaN3

Asymmetrical

225 + 500 mΩ

Development

MasterGaN4

Symmetrical

225 + 225 mΩ

Development

MasterGaN5

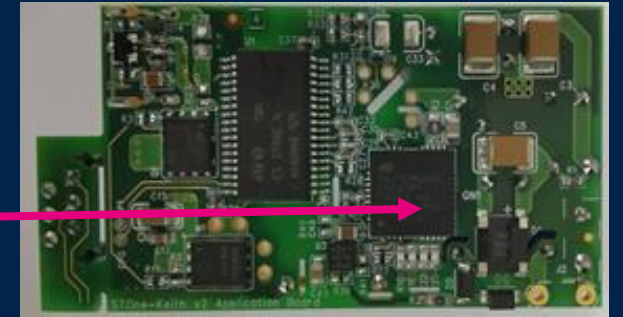
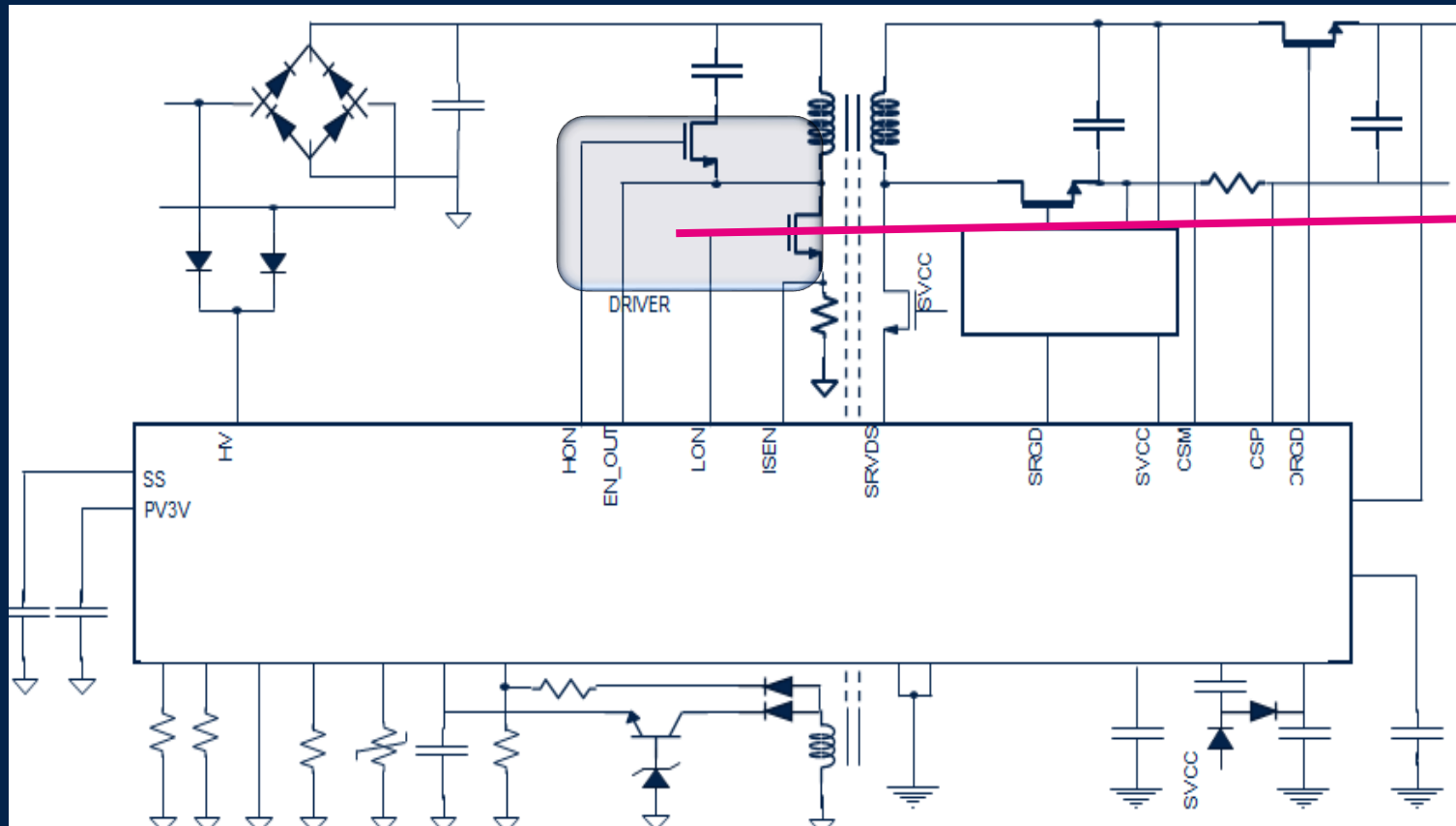
Symmetrical

500 + 500 mΩ

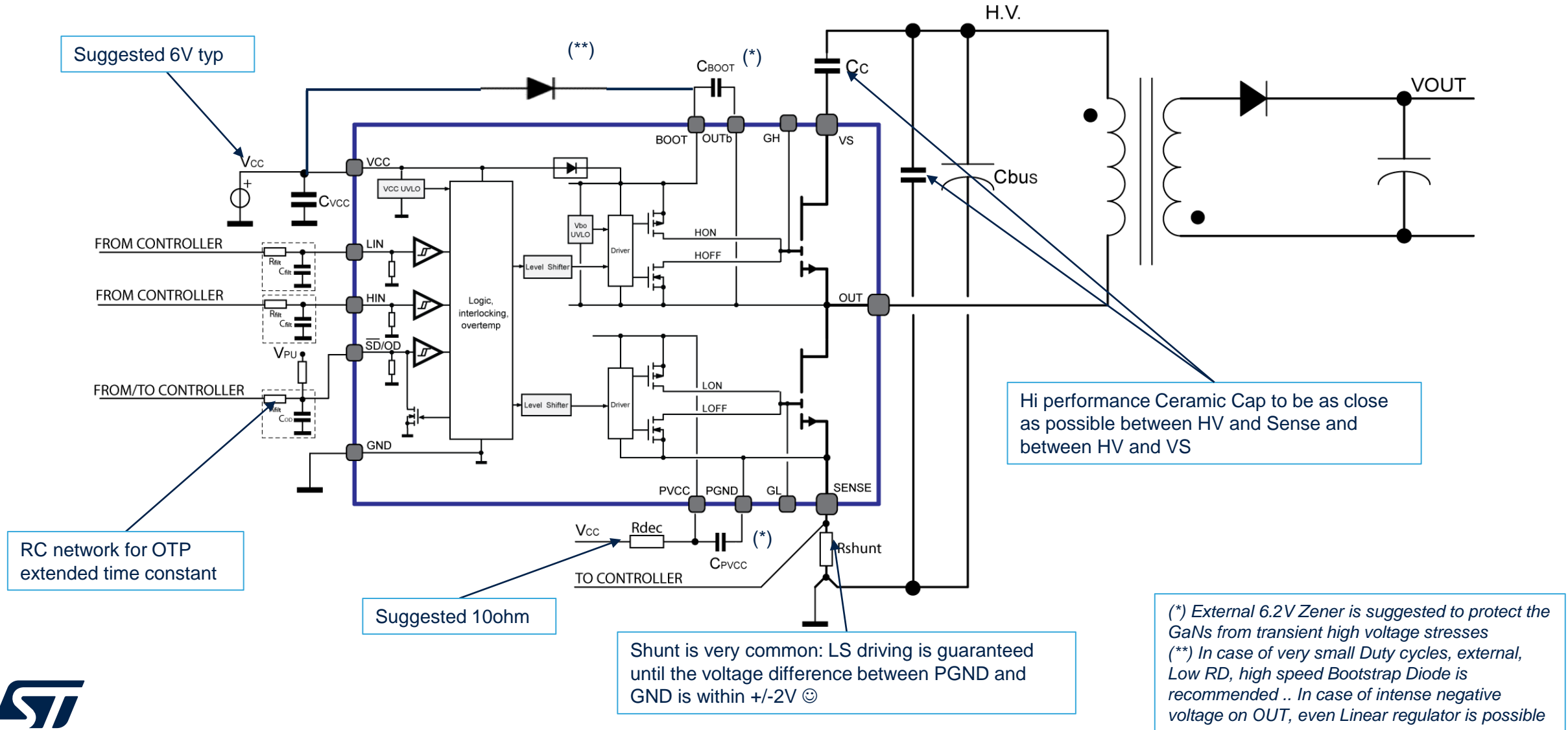
Development

Whole product family to be released by H1 2021

65W ACF Application example - MasterGaN



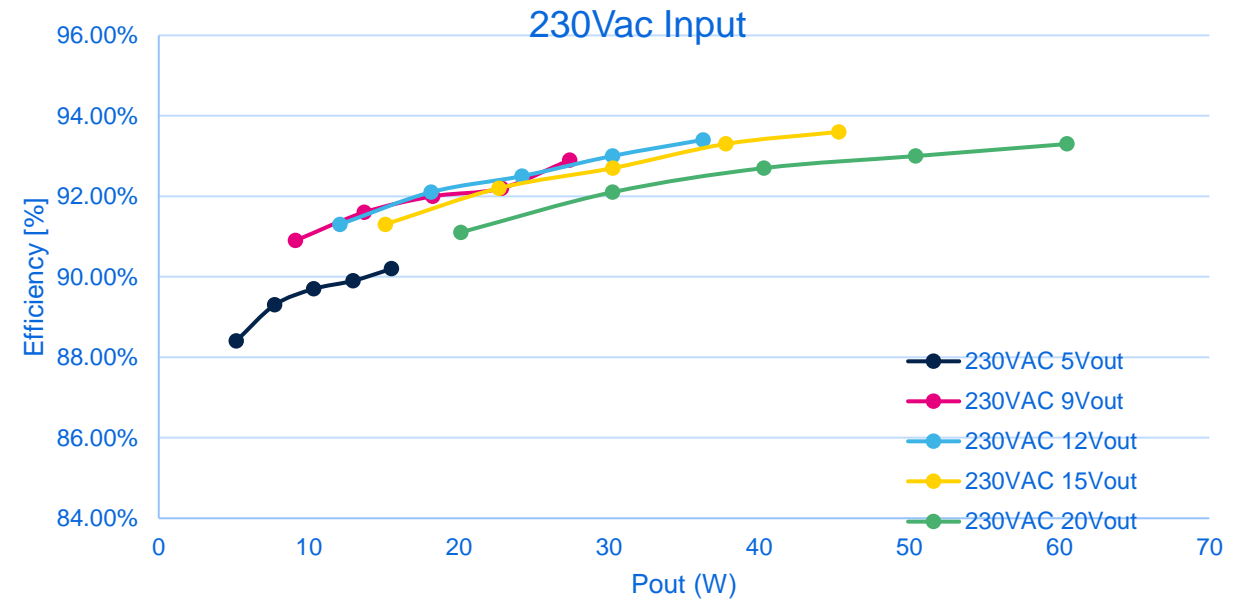
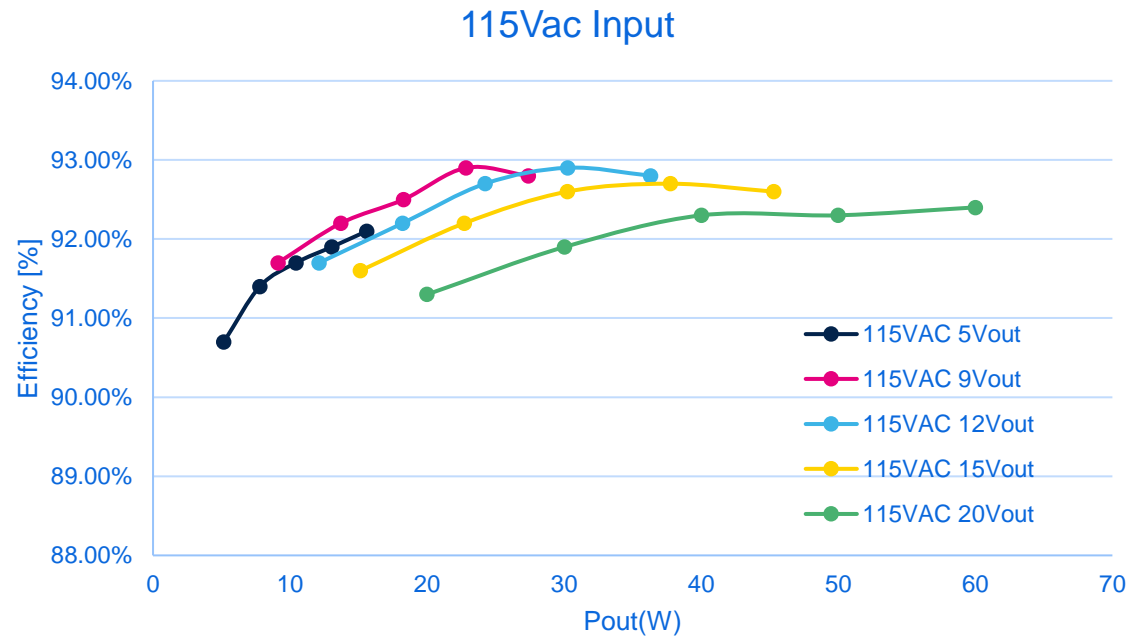
65W ACF Application example typical connection





65W ACF application example efficiency

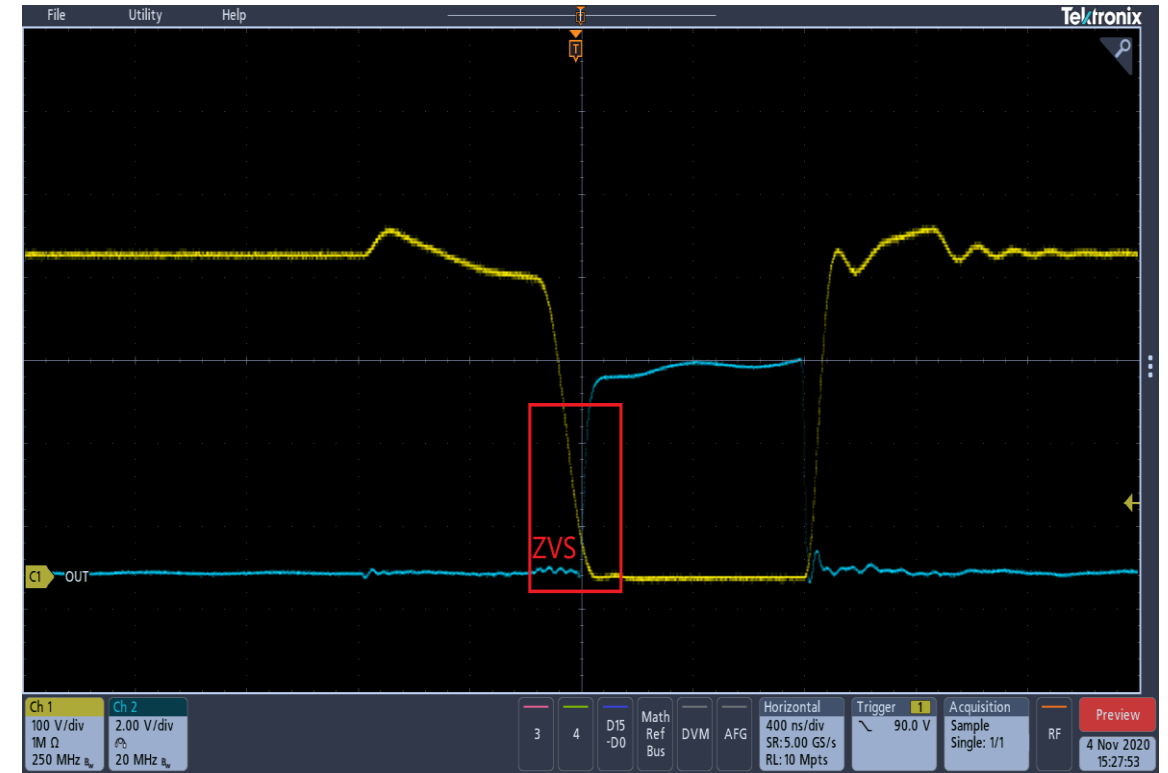
Efficiency performance at low Line and high Line





65W ACF application example typical waveform

230 Vacin 20V/3.25A

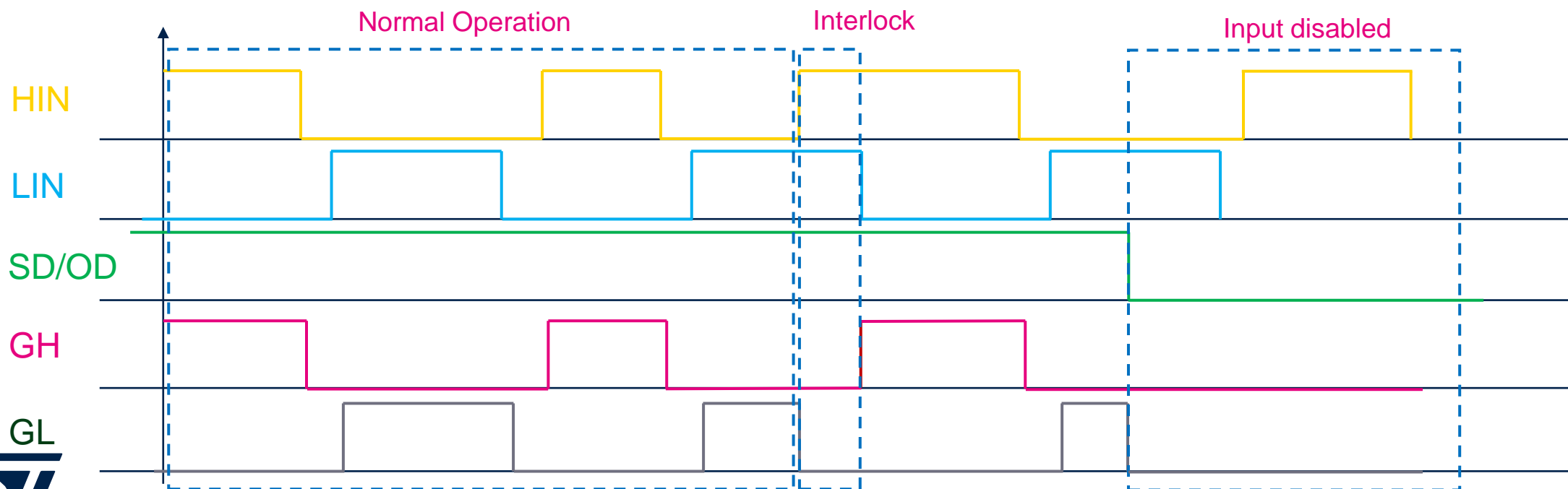




Gate drive logic inputs – truth table

| | Input pins | | | GaN transistors status | |
|---------------------------------|---------------------------|-----|-----|------------------------|-----------|
| | $\overline{\text{SD/OD}}$ | LIN | HIN | LS | HS |
| Disabled input port | L | X | X | OFF | OFF |
| Normal Operation Configurations | H | L | L | OFF | OFF |
| | H | L | H | OFF | ON |
| | H | H | L | ON | OFF |
| Interlocking | H | H | H | OFF | OFF |

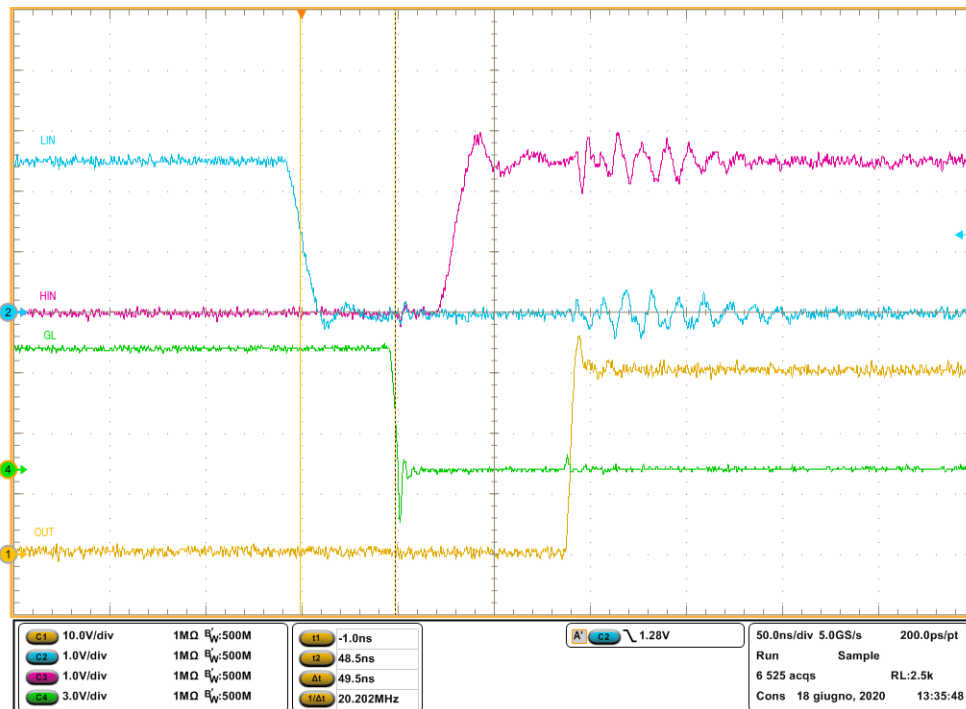
1. X: Don't care



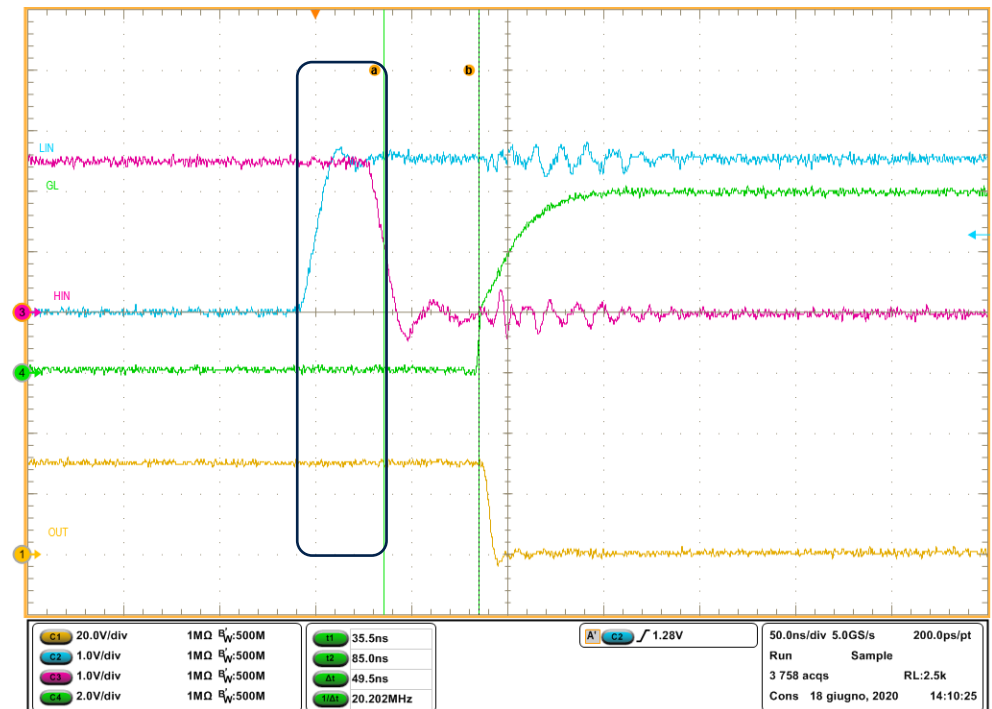


Logic inputs – Interlocking

MASTERGAN has an interlocking feature to prevent contemporary activation of high side and low side.



HIN and LIN high never occurs, normal condition

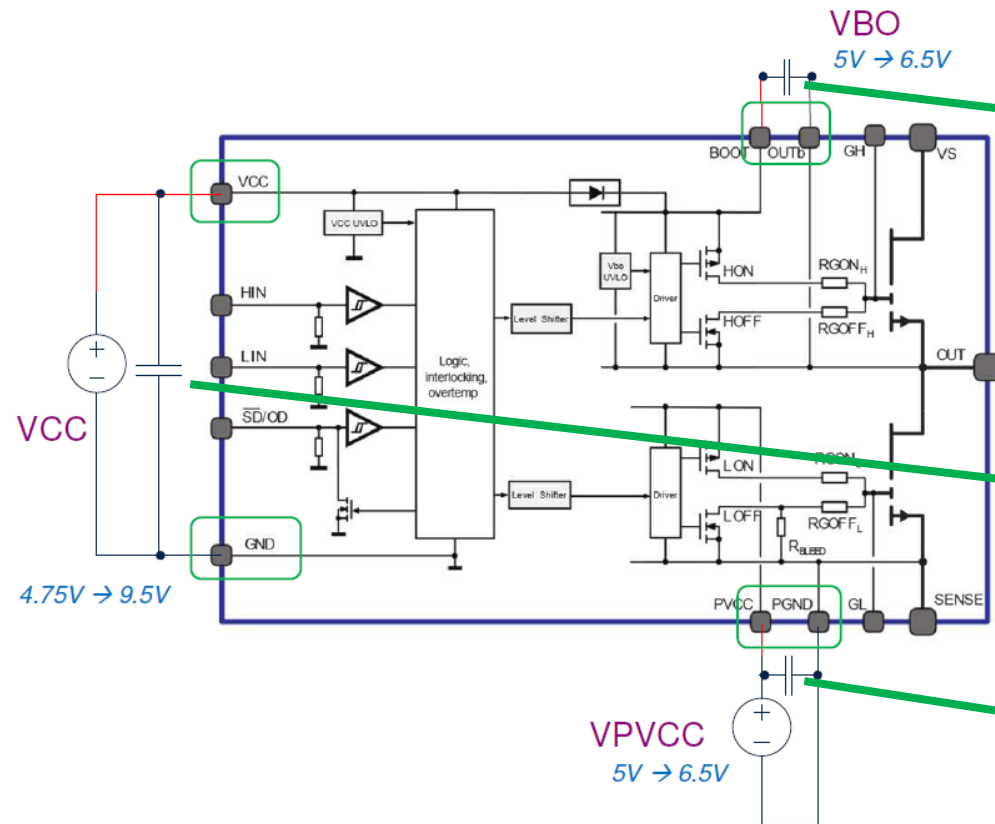


HIN and LIN high in black square → Interlock
GL and GH are both low

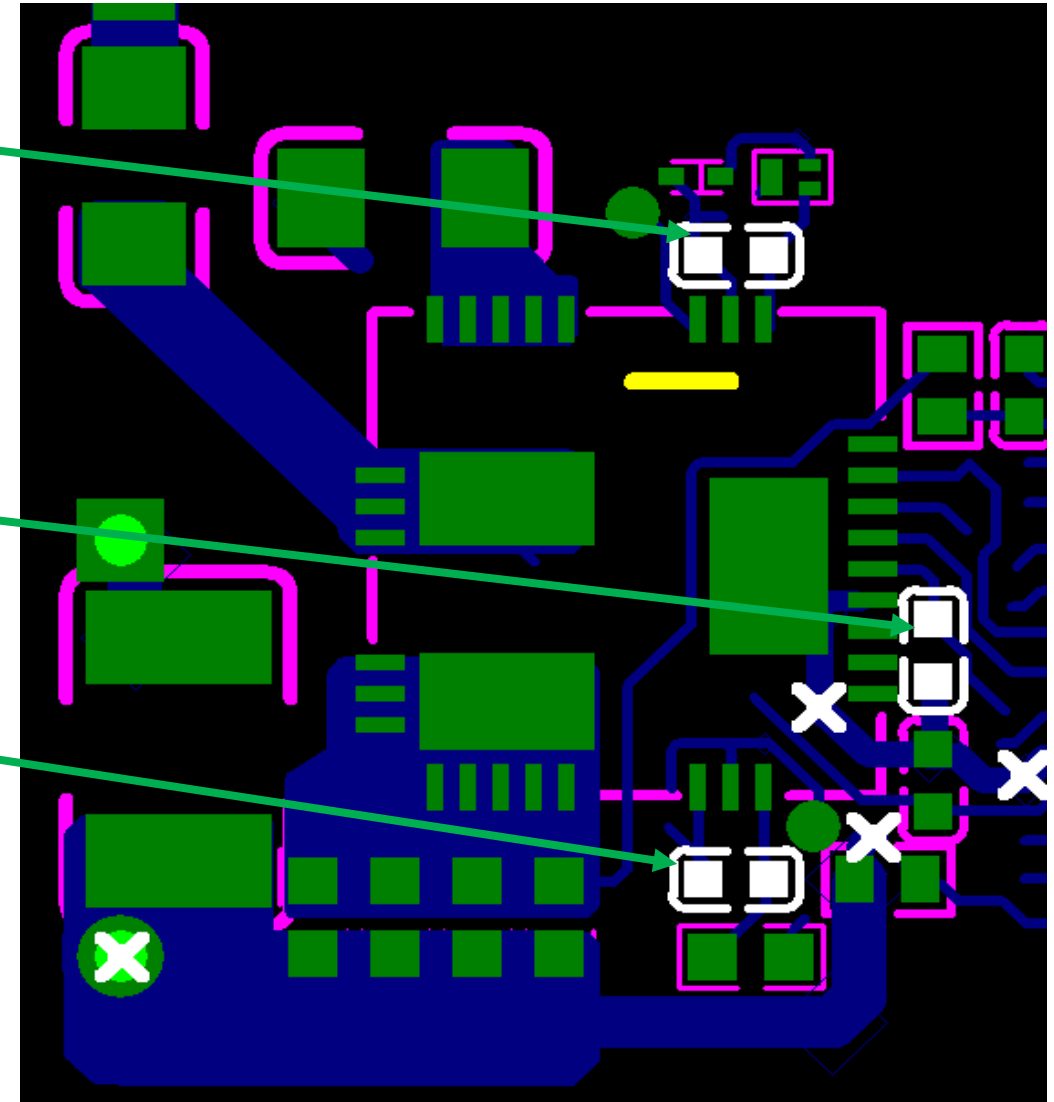
- When Interlock condition is applied to the input, the active driver is shut down after T(OFF)
- When Interlock condition is removed from the input, the new input configuration is applied on the output after T(OFF)



Noise prevent-PCB layout

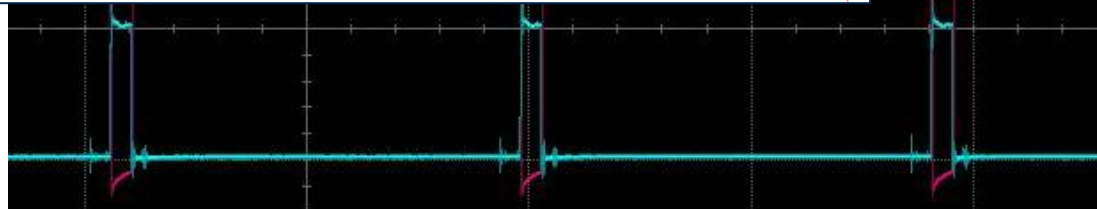
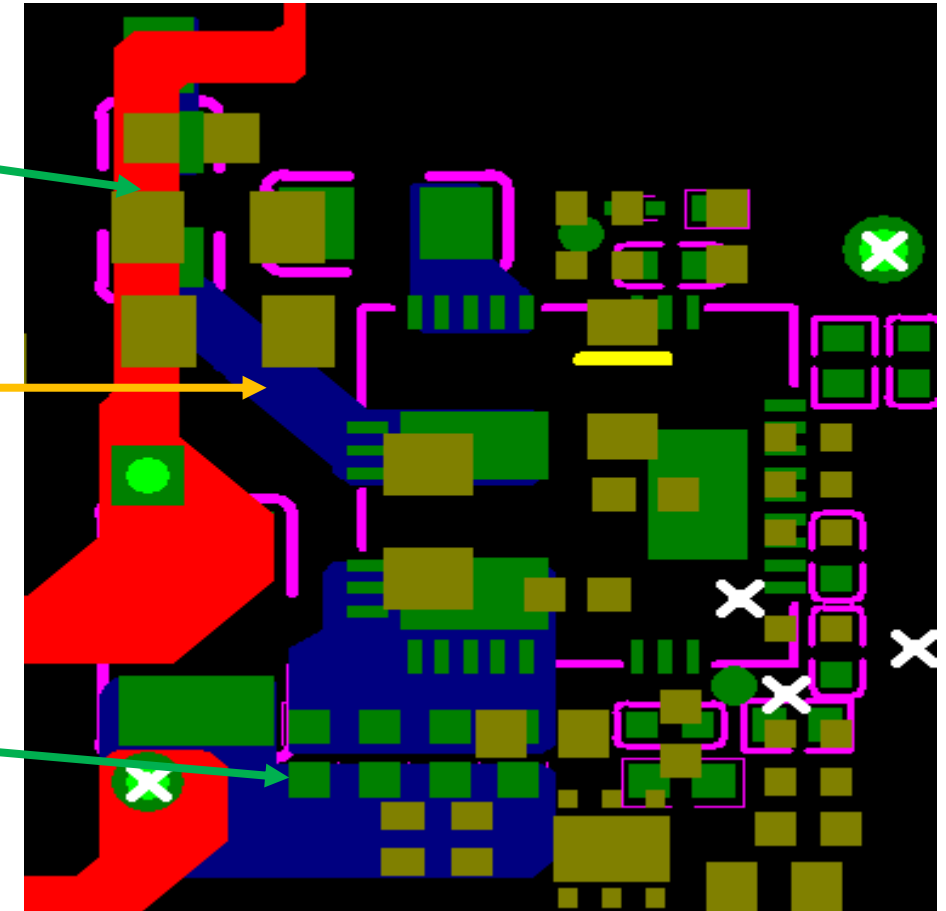
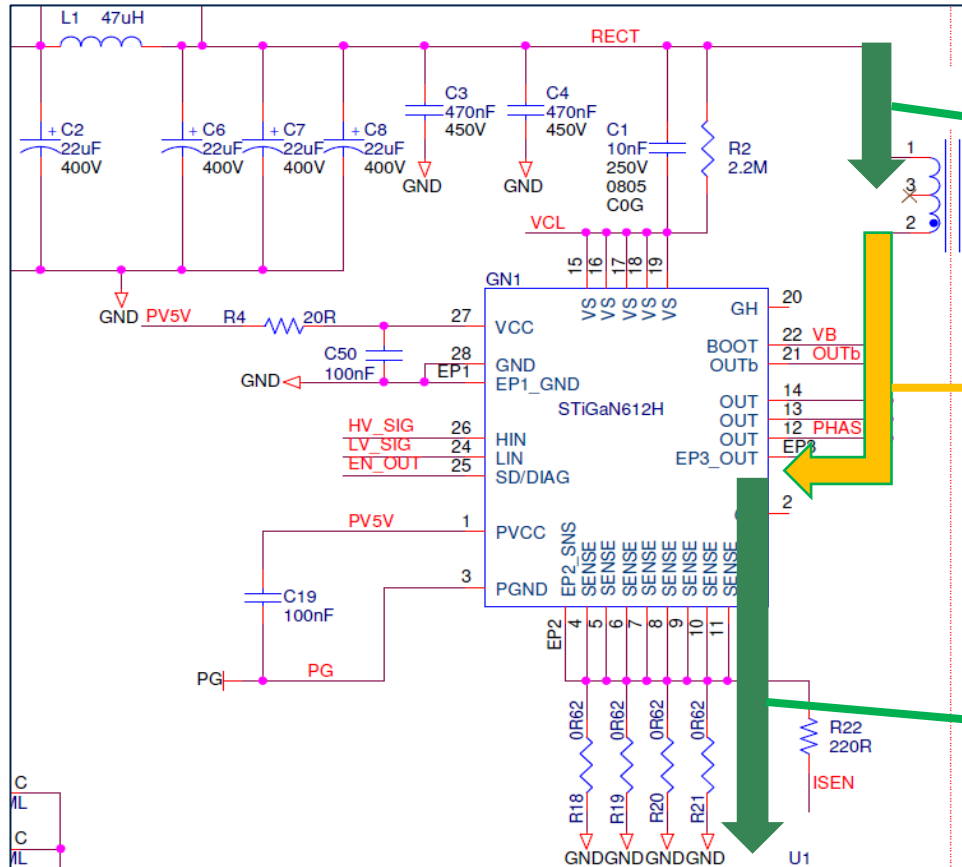


- VCC Filter caps placed to close VCC-GND Pins





Noise prevention - PCB layout

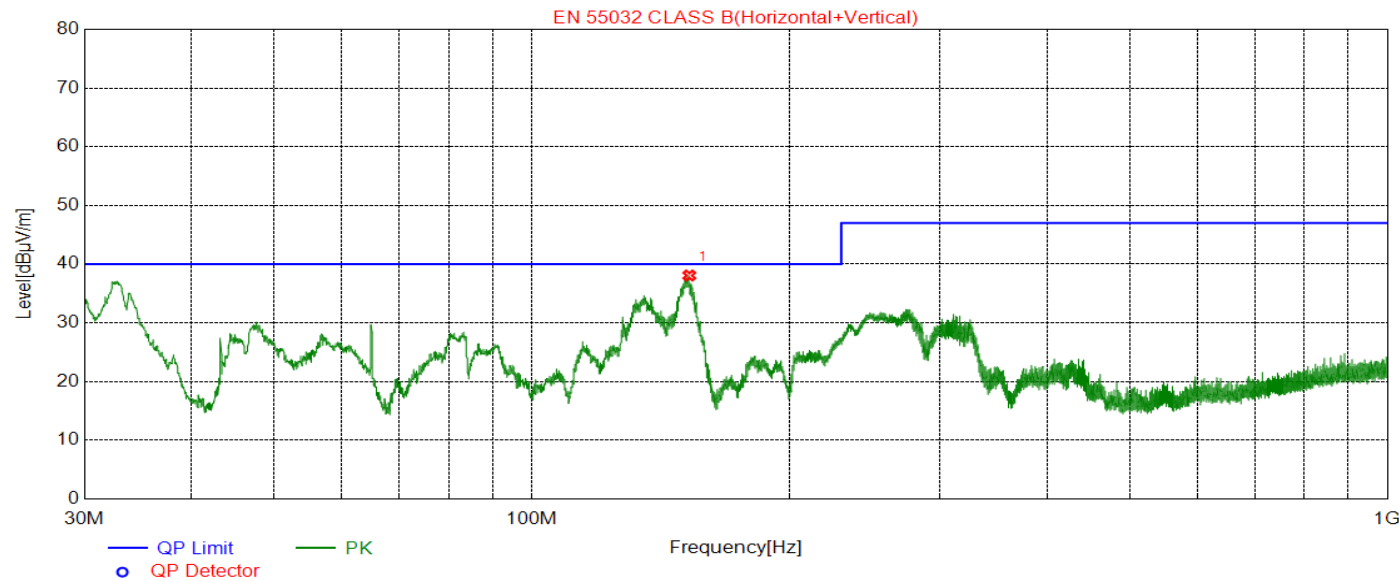


- Keep signals traces away from OUT trace
- Keep bulk voltage—transformer-OUT-SENSE-GND loop as small as possible



dv/dt adjustment

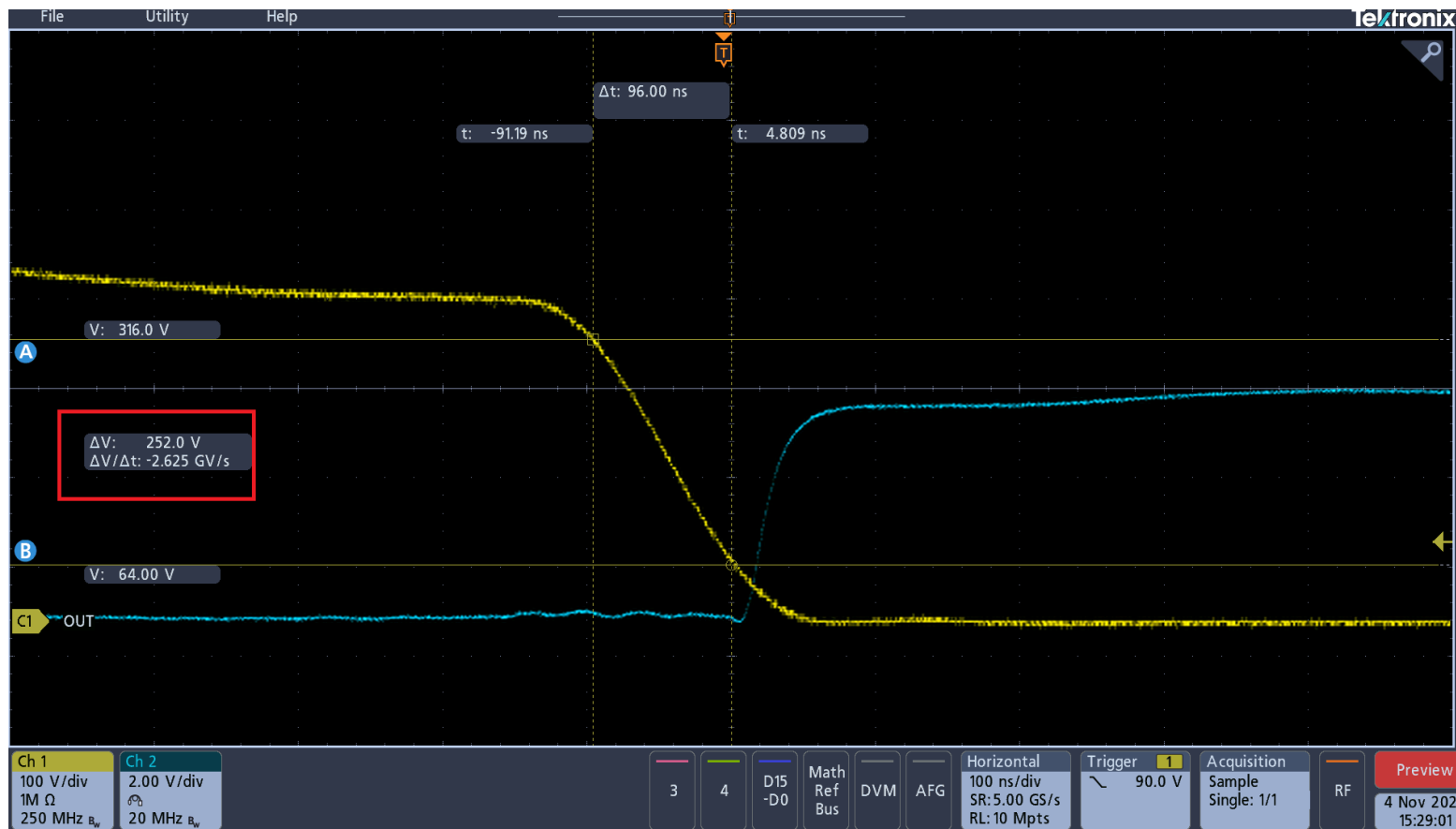
- During the design of power converters, the adjustment of dV/dt of middle point of OUT pin is important to:
 - Reduce EMI
 - To avoid undesired oscillations when parasitic elements cannot be further minimised
 - Reduce secondary side stress





dv/dt adjustment

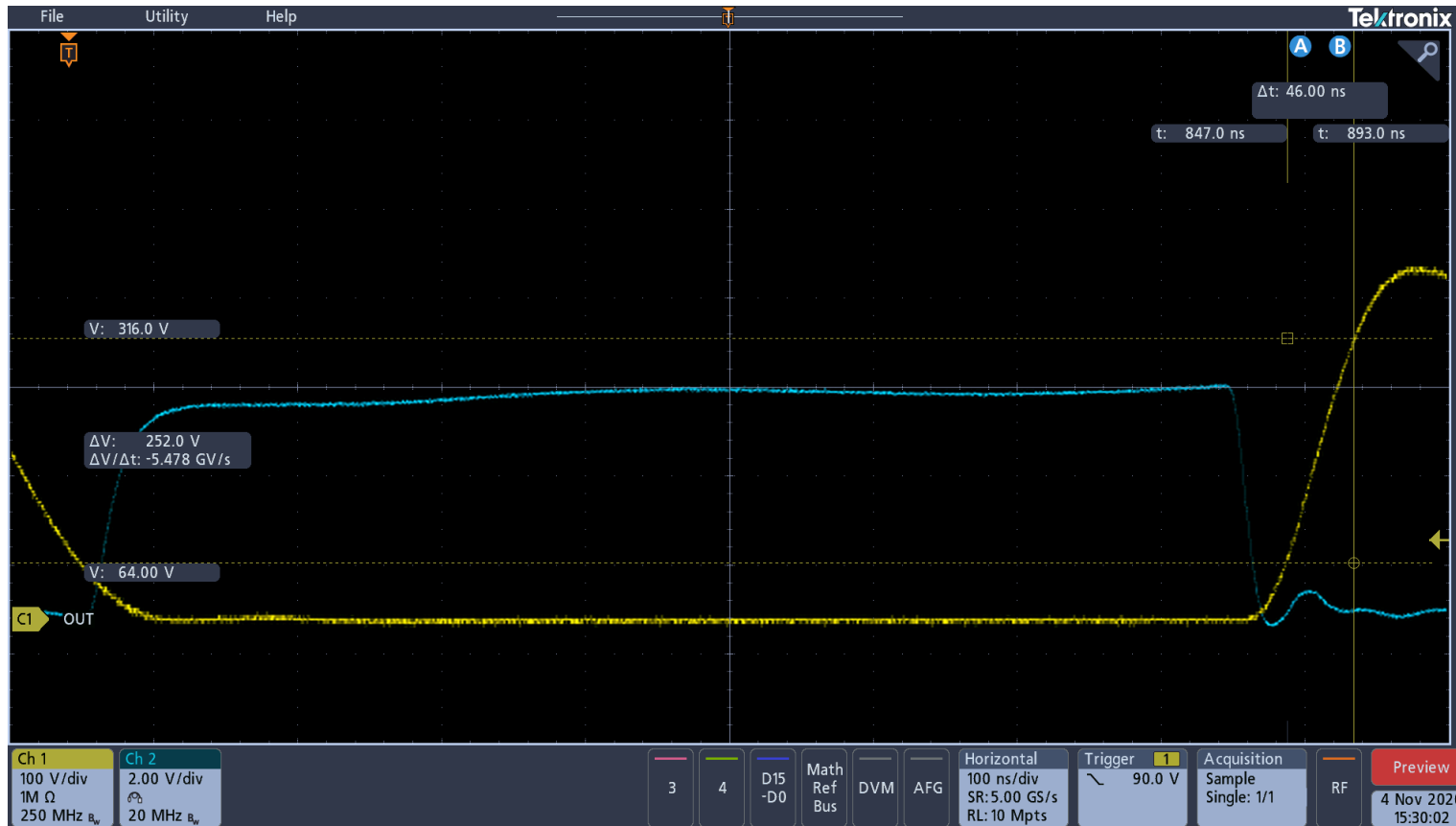
OUT pin dv/dt at turn on: GaN turn-on when resonance has sufficient amplitude to obtain ZVS





dv/dt adjustment

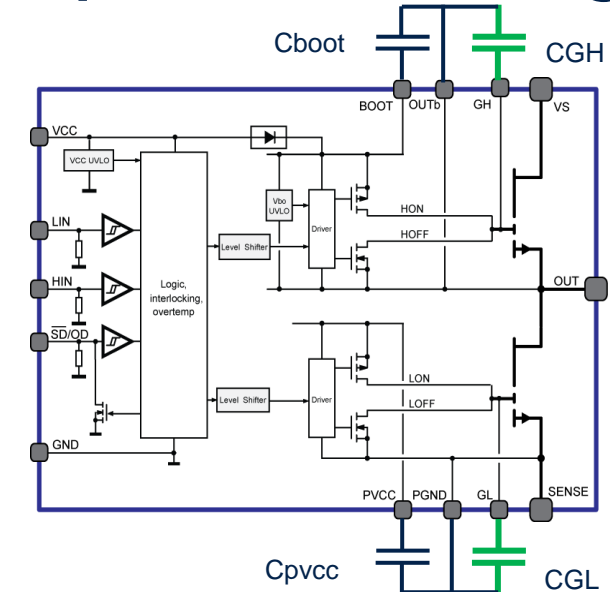
OUT pin dv/dt at turn off: Turn off dv/dt can be reduced using proper selection of MASTERGAN biasing components





dv/dt adjustment adding cap on GaN's gate

- Adding a capacitor between GL (GH) and PGND (OUTb), is equivalent to increase GaN's Gate Charge
- Maximum value must be found to avoid driver's dynamical overstress and considering the operating frequency F_{sw}
 - $CG_x < 80 \text{ mW} / (P_{vcc}^2 \cdot F_{sw}) - (330 \text{ pF})$



PROs

- Fine tuning of the obtained effect
- High repeatability of the effect thanks to the accuracy of the available discrete components
- Effect is also on EMI associated with normal operation

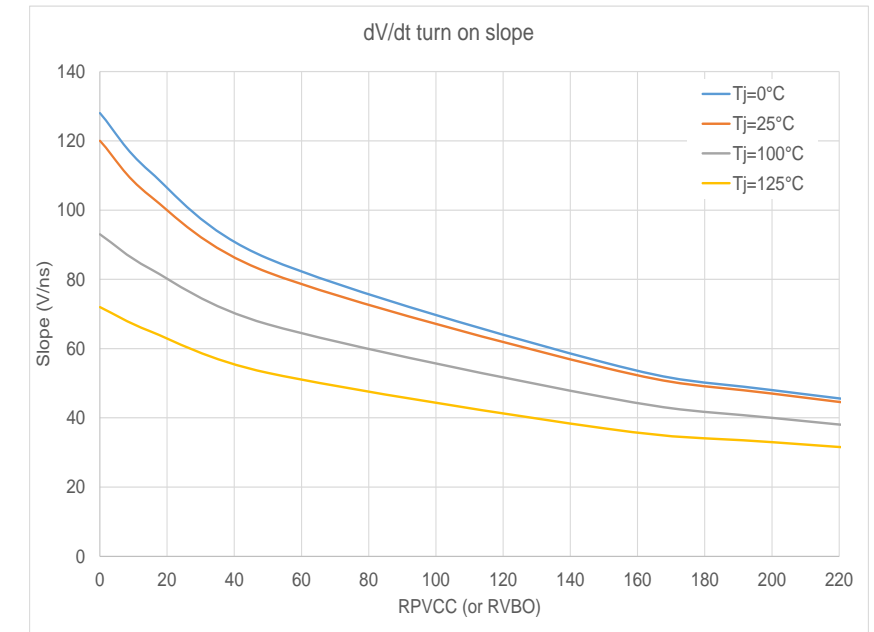
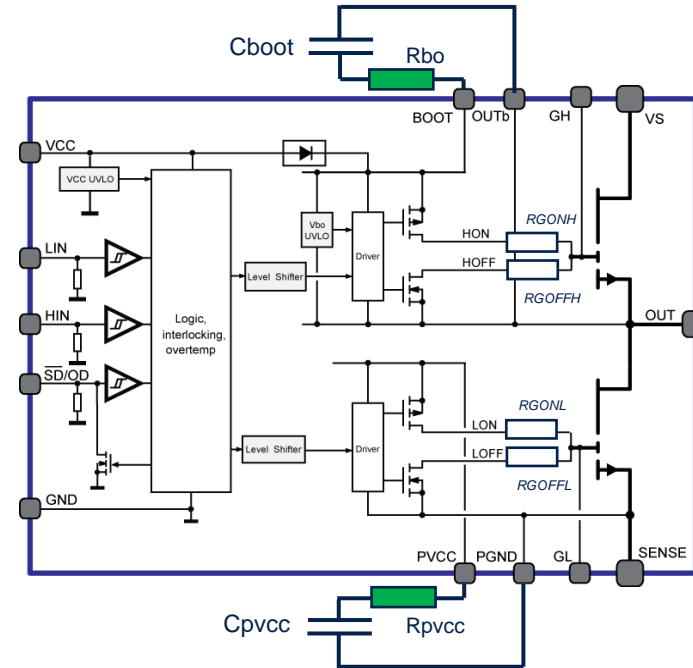
CONs

- Additional operating consumption to PVCC and Vbo, especially at high frequency
- Not suitable for very high frequency solutions



Adding a resistor on PVCC

- A resistor in series with PVCC or VBO decreases the driving current.
- A very short drop is evident on PVCC / VBO at driver turn on.



PROs

- Fine tuning of the obtained effect
- High repeatability of the effect thanks to the accuracy of the available discrete components
- Effect is also on EMI associated with normal operation

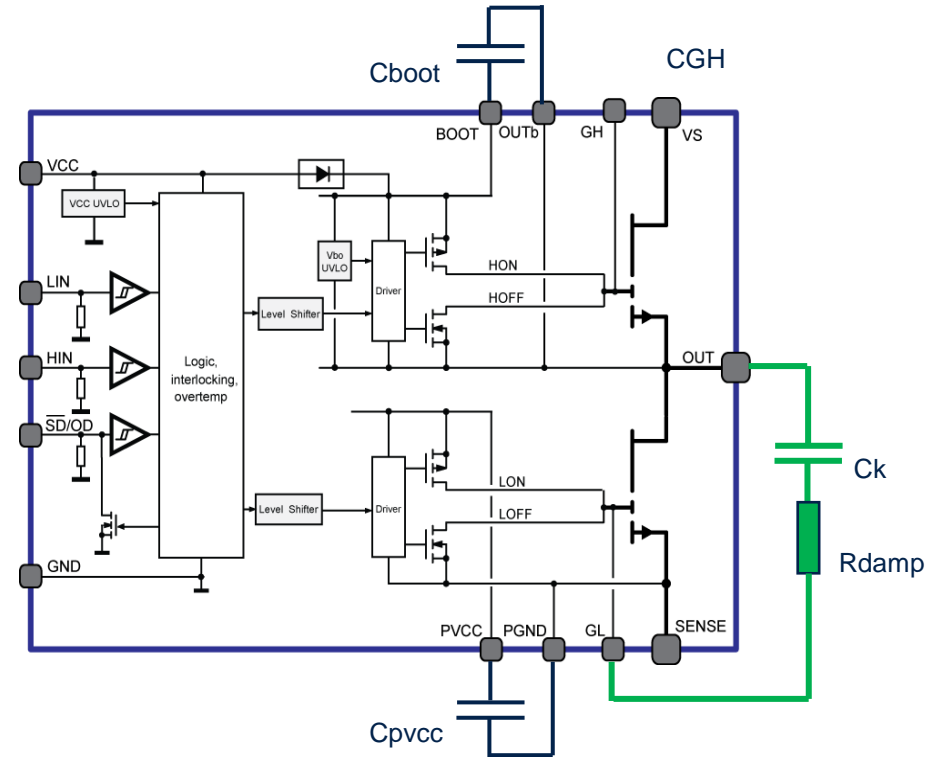
CONs

- PVCC / VBO drop can increase the propagation delay
- Short-on time can result into worse $R_{ds(on)}$ because of the reduced Gan's gate overdrive voltage (i.e. $PVCC - V_{gsth}$)
- Duration of VBO drop must be shorter than 2 μs to prevent UVLO activation



dv/dt Adjustment - adding dv/dt killer

- An RC network feedback can be added between OUT node and GL in order to reduce the GL voltage in case of intense negative dv/dt.
 - Consider to use PCB, especially for thin PCBs, instead of the added Ck
- Example
- 0.8mm 4 layer PCB, 0.1mm inner core thickness, $\epsilon_r=4.4$
 - 10pF \rightarrow 30mm²: can fit below MasterGaN



PROs

Acts on high dv/dt only: the dv/dt value is then balanced over entire operating conditions

CONs

High voltage component needed



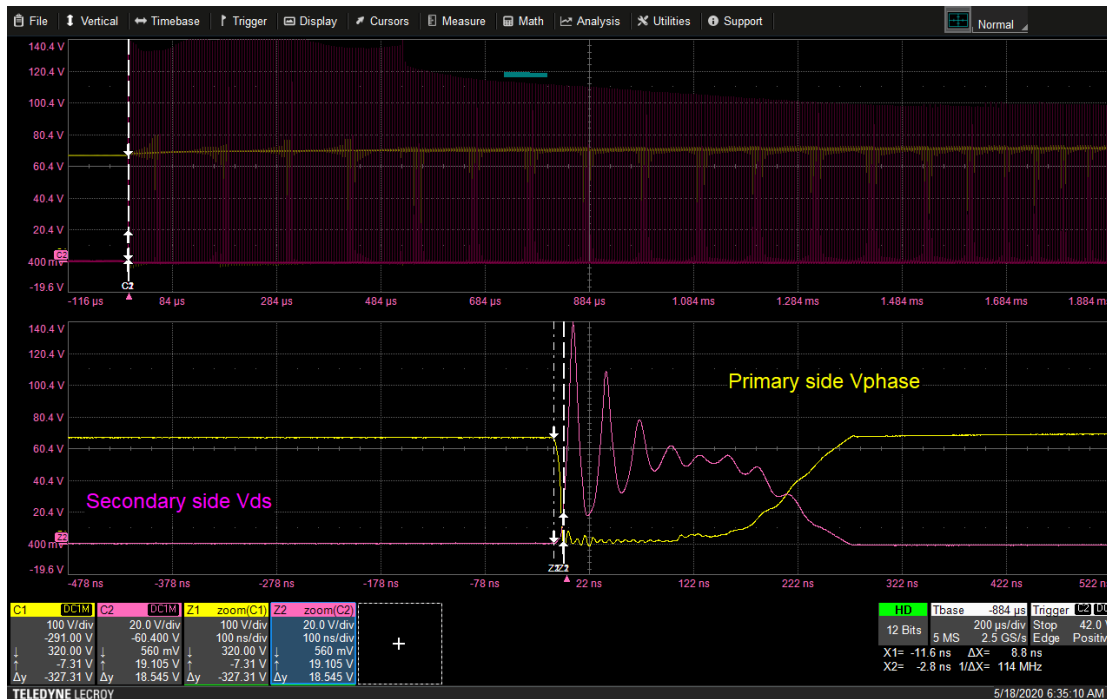
Adding dV/dt limiter – design tips

- The value of the Capacitor (C_k) limits the dV/dt during hard switching thanks to Miller effect
 - During turn on the rate is limited to $\sim \frac{V_{PVCC} - V_{TH}}{R_{ONG} C_k} = \frac{V_{PVCC} - 1.7}{50 \cdot C_k}$
 - During turn off, it is limited to $\sim \frac{V_{TH}}{R_{OFFG} C_k} = \frac{0.85}{C_k}$
- A resistor in series is required to avoid oscillations due to stray inductance
 - $R_{DAMP} \gg \sqrt{\frac{L_{stray}}{C_k}}$
- Capacitor required is typically 5pF to 10pF (600V rated)
 - E.g.: Using $PVCC = 6V$ and $\max dV/dt = 10V/ns \rightarrow C_k = 8.6pF$

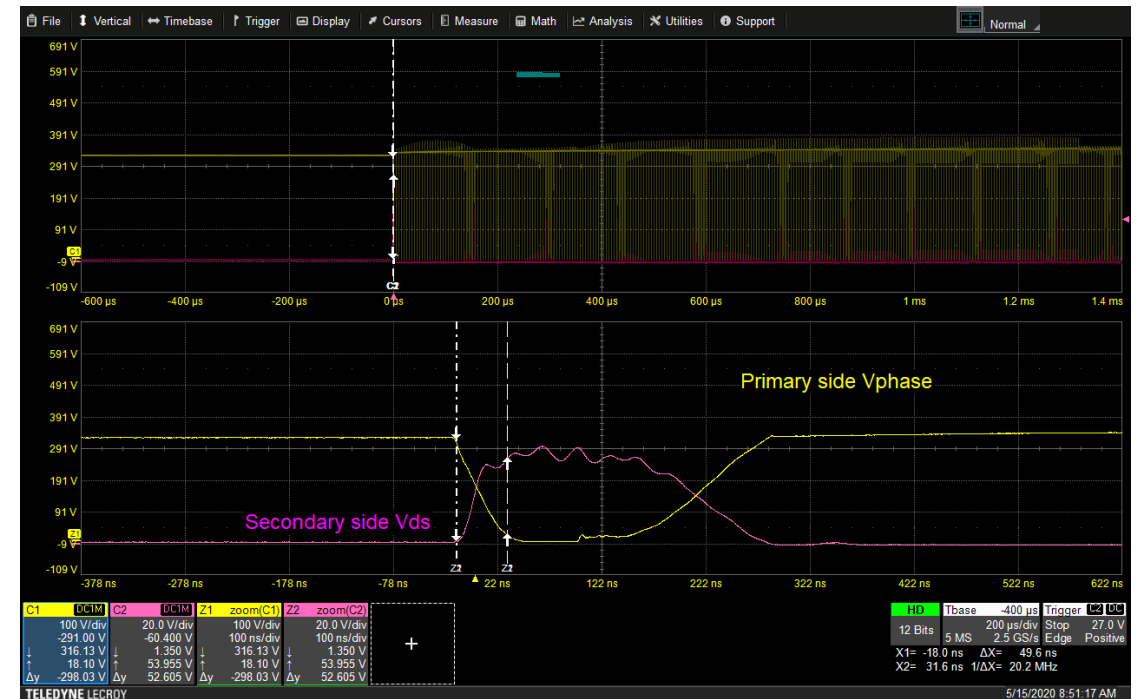


dv/dt adjustment - adding dv/dt killer

- Startup waveforms at 230VAC compared
 - dV/dt changed from original 37v/ns to 6v/ns



Original
dV/dt equal to 37V/ns

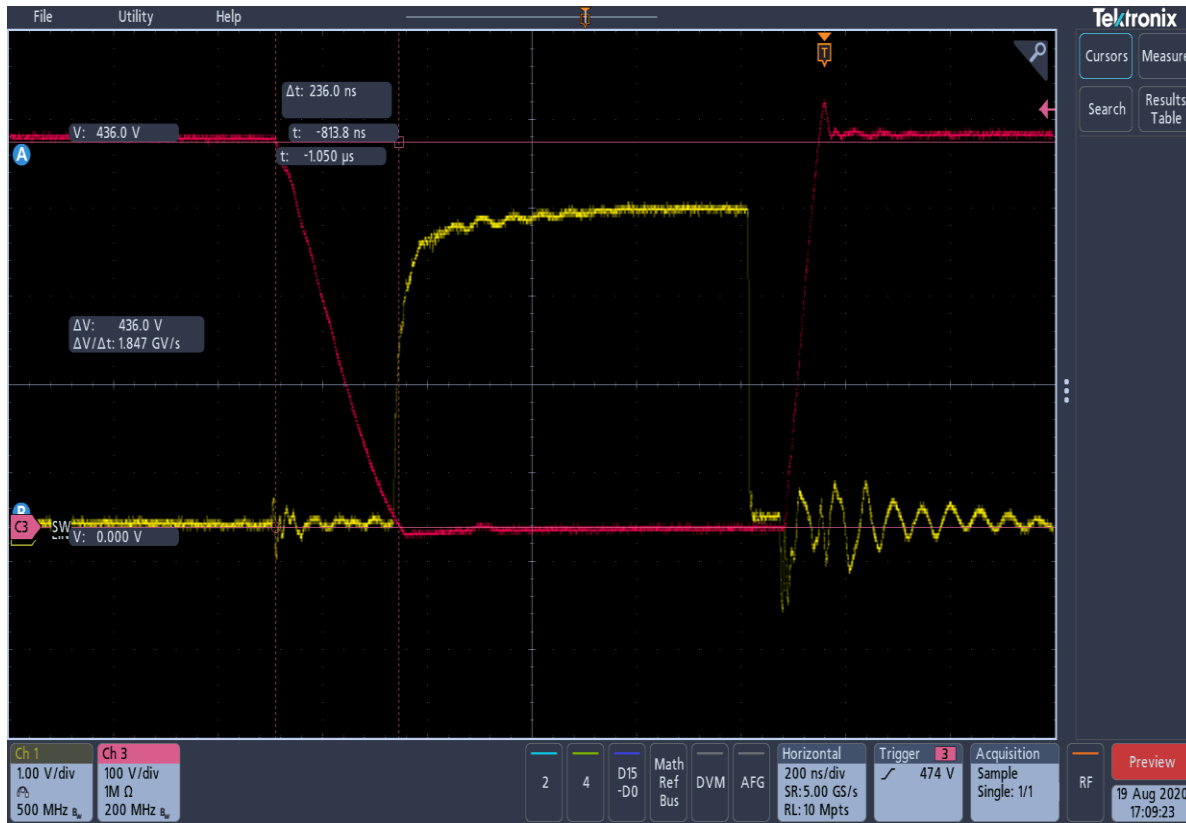


With dV/dt limiter cap 10pF / 200Ω
dV/dt limited to 6V/ns

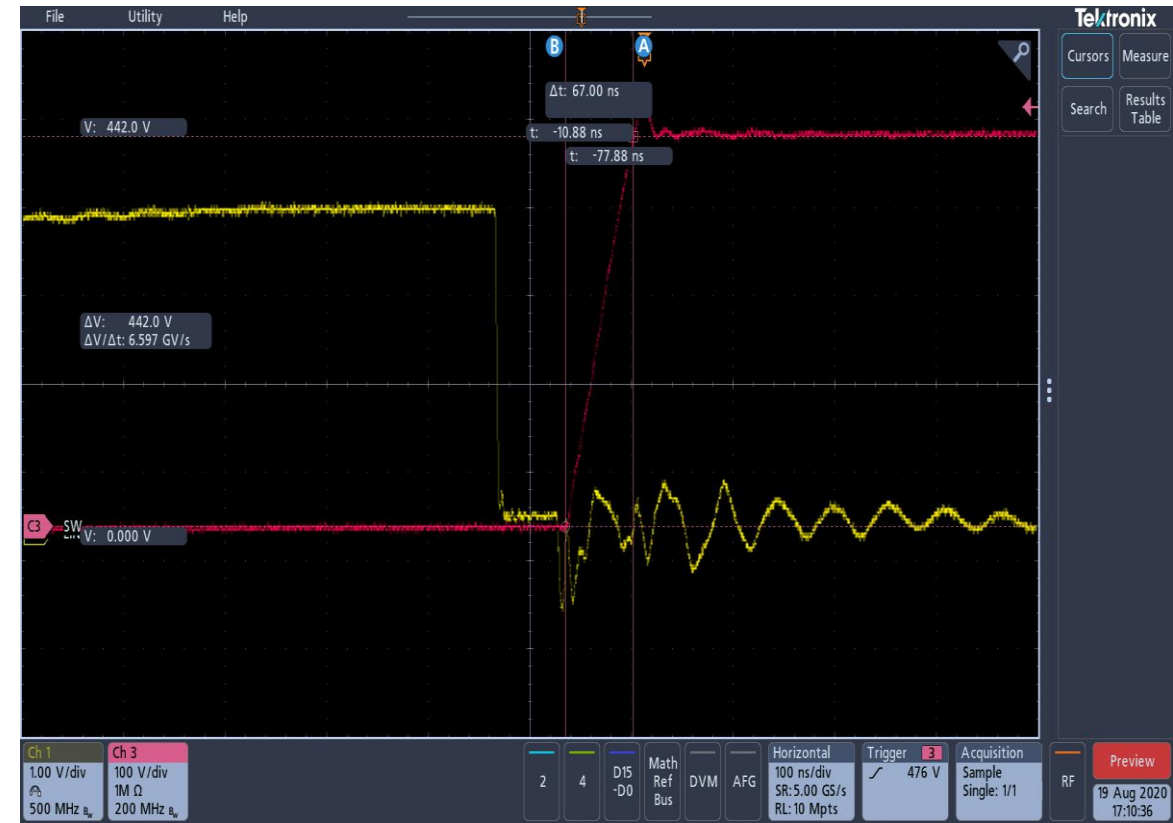


dv/dt adjustment - adding dv/dt killer

Example of the 65W board: $R_{pvcc}=15\Omega$ $C_g=470pF$ $R_{43}=200\Omega$ $C_{57}=10pF$
220V/50Hz input 20V/3.25A output



Turn on: 1.85V/nS



Turn off: 6.6V/nS



Thank you